

REMARKS

This application has been carefully reviewed in light of the office action mailed November 21, 2001. Claims 1-3 and 6-9 are pending in this application. Applicants respectfully request early and favorable acceptance of this application.

Rejections under 35 U.S.C. § 102

Claims 1-9 are rejected under 35 U.S.C. § 102(e) as being anticipated by Ooyama et al., U.S. Patent No. 6,191,494. Applicants respectfully traverse the rejection.

Claim 1 as amended recites an electronic device (e.g., 800) that includes a leadframe having a die carrier (e.g., 106) and a plurality of leads (e.g., 108) having bump indentations (e.g., 110). A semiconductor die has a surface supported by the die carrier, wherein the surface is formed with a plurality of conductive bumps (e.g., 802) for directly attaching to the plurality of bump indentations.

The Ooyama et al. reference discloses a semiconductor chip 52 with a first surface mounted on a metal film 58 with a conductive adhesive 59. Wire bonds 54 electrically couple circuitry on a second surface of the semiconductor chip to mounting protrusions which are plated with conductive material 56 to function as external leads.

The reference does not disclose a leadframe having a die carrier and leads with bump indentations, and a semiconductor die with a surface supported by the die carrier and formed with a plurality of conductive bumps for directly attaching to the plurality of bump indentations. The reference discloses a chip with a first surface for mounting to a metal film and a second surface for wire bonding to the external leads, not a die with a single surface supported by a die carrier and

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formed with conductive bumps for attaching to indentations in the leads, i.e., in a flip chip fashion. Consequently, the reference device does not have a low cost and reduced lead inductance of the claimed device which avoids the need for wire bonds.

Therefore, Applicants believe the rejection under 35 U.S.C. § 102 is overcome.

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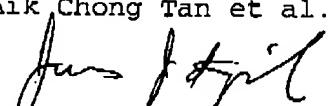
CONCLUSION

Applicant has made an earnest attempt to place this case in condition for allowance. In light of the remarks set forth above, Applicants respectfully request reconsideration and allowance of claims 1-3 and 6-9.

While no fees are believed due, the Commissioner is hereby authorized to charge any fees or credit any overpayment to Deposit Account 501086.

If there are matters which can be discussed by telephone to further the prosecution of this Application, Applicants invite the Examiner to call the undersigned attorney at the Examiner's convenience.

Respectfully submitted,
Aik Chong Tan et al.


James J. Stipanuk
Attorney for Applicant(s)

Reg. No. 44,358
Tel. (602) 244-4885

ON Semiconductor
Law Dept./MD A700
P.O. Box 62890
Phoenix, AZ 85082-2890

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